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LaMCos Wave-Packet Propagation in Silicon Nano-Composite



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1 Introduction and Configurations

Thermal management becomes more and more important in decreasing the sizes of devices and increasing their density. The evolution of fabrication allows to avoid hot spots using isolating and heat dissipative materials.
Effect of crystalline inclusion rigidity and comparison with bulk amorphous silicon



Crystalline nano-inclusion⁶

2 Simulation Methods

- MD simulation
 - SW⁴ interaction potential for Si
 - LAMMPS³
- ► Wave-Packet excitation²
 - Displacement imposed on central atoms between inclusions

$$u_i = \frac{A}{\omega} sin(\omega(t - 3\tau)) e^{-\frac{(t - 3\tau)}{2\tau^2}}$$







- On propagation/diffusion of excitation
 Varying rigidity
 - Variation of the 3 body interaction
 - $\chi = \frac{E_{Incl}}{E_{Mat}} = 1 \text{ or } 4.6$

4 **Propagation**



Maximum value of E_k along the propagation direction: nano-composite

- Nano-composite
- Increasing acoustic mismatch intensifies attenuation
 - Most important at low frequencies
 - Local maximum of E_k between inclusions



Unit Cell⁵

- Polarization
 - Longitudinal
 - Propagation analysis
 - Random
 - Diffusivity computation



Evolution of a wave-packet with ω =3.65 THz and χ =4.6

3 Kinetic Energy Distribution

- Kinetic energy maps as a function of time and position
 - For frequencies between 0.5 and 11 THz
 - Iower limit due to resolution
 - higher limit due to energy propagation limitation
- Propagation/Diffusion
- Pinning between inclusions



- Stronger attenuation in the matrix
- Ballistic at low frequencies/diffusive at higher frequencies
- Amorphous
 - Stronger propagation at low frequencies
 - Higher attenuation at higher frequencies



Bulk amorphous

6 Consequences on the thermal conductivity

- For phonons below the loffe-Regel criterium the thermal conductivity is defined by
 - $\kappa_{prop} = \int_0^{\omega_{IR}} C(\omega, T) v(\omega) l(\omega) g(\omega) d\omega$
- For phonons above the loffe-Regel we have
- $\kappa_{diff} = \int_{\omega_{IR}}^{\infty} D(\omega)C(\omega, T)g(\omega)d\omega$ • The higher the mismatch, the stronger the reduction



Time evolution of kinetic energy distribution for different frequencies

5 Diffusivity

- Randomly polarized excitations allows the computation of the diffusivity¹
 - From the MSD of the energy front $R^2(t) = \frac{1}{E_{tot}} \sum_{i=1}^{N} x_i^2 E_i(t)$
 - Diffusivity defined by the slope $R^2(t) = 2D(\omega)t$



- Small discrepancies between χ =1,4.6 or bulk amorphous
- Highly dependent on the glass structure

7 Conclusion



Inclusion effect mostly sensible on κ_{prop}^{7}

Small effect on the conductivity at 300K Through wave packets excitation simulations we have separately computed the propagative and diffusive parts of heat conduction. Though propagation is lowered by the rigid inclusions, the diffusion tends to be increased. This work can be continued with the study of different nano-composites.

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